

The 2nd International Conference on Integrated Circuits and Microsystems



第二届集成电路与微系统国际会议

November 8-11, 2017 | Nanjing, China

2017年11月8-11日 | 中国.南京

ICICM 2017

Engineering Village



ELSEVIER
SCOPUS

Submission Deadline: July 30, 2017

=Conference Venue=

Southeast University, Nanjing, CHINA

Sipailou 2#, Nanjing, Jiangsu Province, 210096 P. R. China

ABOUT

ICICM 2016 proceedings have been indexed by EI COMPENDEX and SCOPUS, CPCI (Web of Science).

All accepted papers after proper presentation and registration will be collected in the conference proceedings, which will be submitted and reviewed in the **IEEE Xplore, Ei Compendex, and Scopus**

CONFERENCE SCOPE

Digital, Analog, Mixed Signal IC and SOC design technology
Silicon integrated circuits and manufacturing
Low-power, RF devices & circuits
IC Computer-Aided –Design technology, DFM
Silicon/germanium devices and device physics
Interconnect, Low K, High K and other process technologies
Unconventional and nano-electronics
Organic semiconductor devices and technologies
Compound semiconductor devices and circuits
Displays, sensors and MEMS
Semiconductor materials and material characterization
Packaging and testing technology
Solar cell & other devices for new energy sources
Modeling and simulation
Equipment technolog
Reliability
Displays, sensors and MEMS
Advance memories technology (Flash, FeRAM, PCM, ReRAM, MRAM etc.)

KEYNOTE

- *Prof. Qiang Li
--University of Electronic Science and Technology of China, China
- *Prof. Gene Eu (Ching Yuh) Jan
--National Taipei University, Taiwan
- *Prof. Xiaoxiao Wang
--BeiHang University, China
- *Prof. Dai Yong-Sheng
--Nanjing University of Science & Technology, China

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